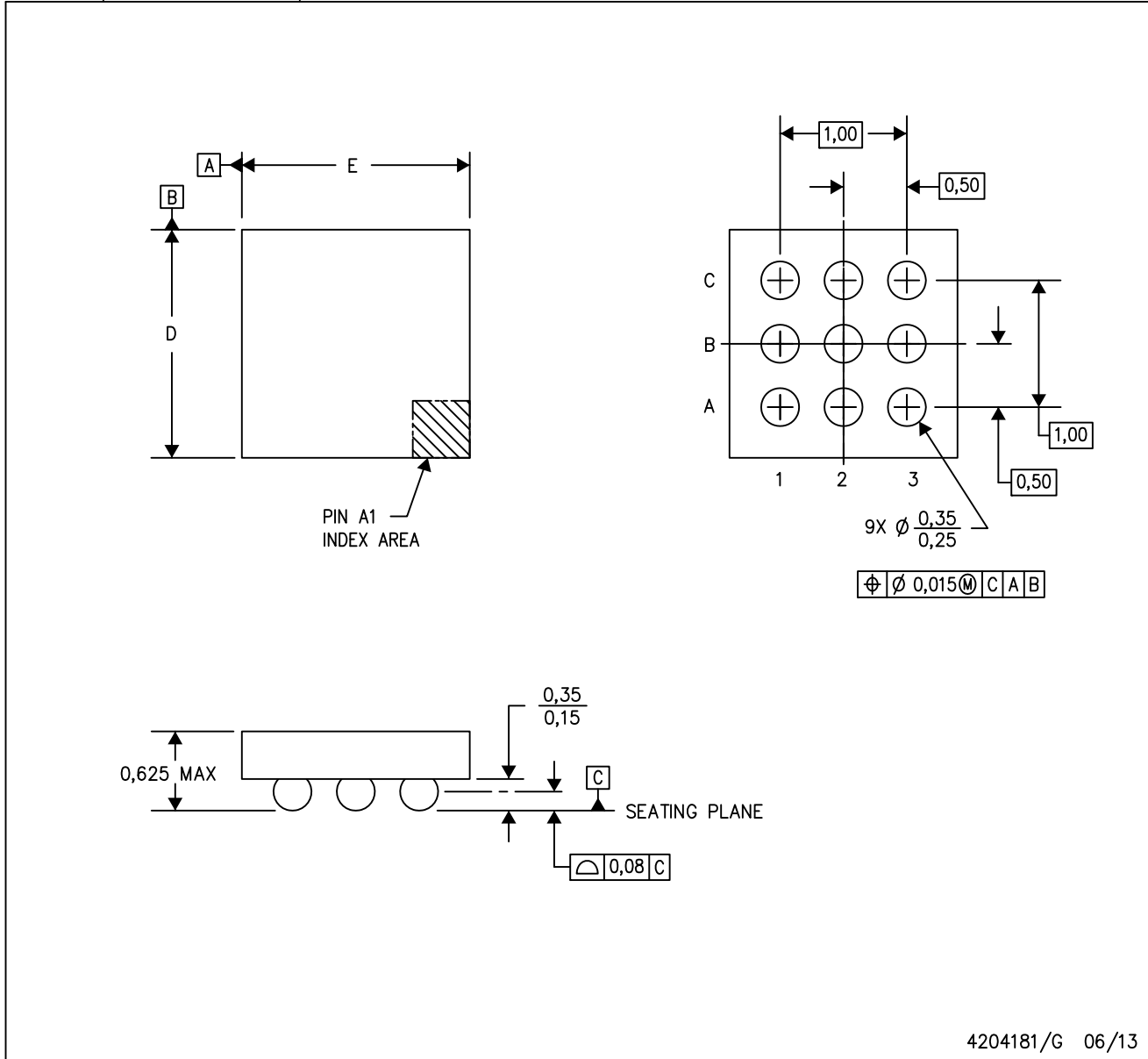


YEF (S-XBGA-N9)

DIE-SIZE BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. NanoStar™ package configuration.

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